Materials Declaration

Package	SOIC
Body Size	300 mils
LeadCount	24
Option	PbFree - Batwing

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	5.9	2.77 E-02	41811
SiO2 Filler	87	4.12 E-01	621816
Phenol Resin	3	1.42 E-02	21442
Antimony_Sb2O3	4.15	1.97 E-02	29661

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.72 E-01	259414
Fe	2.35	4.15 E-03	6252
P	0.03	5.30 E-05	80
Zn	0.12	2.12 E-04	320

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.41 E-03	2131

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.43 E-03	6687

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.50 E-04	1282

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.66 E-03	7030

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	20	2.75 E-04	415
Ag Filler	75	1.03 E-03	1555
Aromatic Amine	5	6.90 E-05	104

Package Totals

Weight (g)	PPM
6.63 E-01	1000000

Molding Compound

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Die Attach Paste

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

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any inaccuracy of such information.

Materials Declaration

Package	SOIC
Body Size	300 mils
LeadCount	24
Option	SnPb - Batwing

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	5.9	2.77 E-02	41788
SiO2 Filler	87	4.12 E-01	621474
Phenol Resin	3	1.42 E-02	21431
Antimony_Sb2O3	4.15	1.97 E-02	29645

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.72 E-01	259271
Fe	2.35	4.15 E-03	6249
P	0.03	5.30 E-05	80
Zn	0.12	2.12 E-04	320

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.41 E-03	2130

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.08 E-03	6148
Pb	15	7.20 E-04	1085

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.50 E-04	1281

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.66 E-03	7026

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	20	2.75 E-04	414
Ag Filler	75	1.03 E-03	1554
Aromatic Amine	5	6.90 E-05	104

Package Totals

Weight (g)	PPM
6.63 E-01	1000000

Molding Compound

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Die Attach Paste

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

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Materials Declaration

Package	SOIC
Body Size	300 mils
LeadCount	24
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	3.95 E-02	62281
SiO2 Filler	85	3.35 E-01	529390
Phenol Resin	3	1.18 E-02	18684
Antimony_Sb2O3	1.5	5.92 E-03	9342
Brominated Resin	0.5	1.97 E-03	3114

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.97 E-01	310453
Fe	2.35	4.74 E-03	7483
P	0.03	6.05 E-05	96
Zn	0.12	2.42 E-04	382

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.82 E-03	2868

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.27 E-03	6739

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.02 E-03	1610

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.79 E-02	43991

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.65 E-04	892
Ag Filler	75	1.70 E-03	2675

Package Totals

Weight (g)	PPM
6.34 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

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ADI Proprietary

Materials Declaration

Package	SOIC
Body Size	300 mils
LeadCount	24
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	3.95 E-02	62281
SiO2 Filler	85	3.35 E-01	529390
Phenol Resin	3	1.18 E-02	18684
Antimony_Sb2O3	1.5	5.92 E-03	9342
Brominated Resin	0.5	1.97 E-03	3114

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.97 E-01	310453
Fe	2.35	4.74 E-03	7483
P	0.03	6.05 E-05	96
Zn	0.12	2.42 E-04	382

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.82 E-03	2868

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.63 E-03	5728
Pb	15	6.41 E-04	1011

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.02 E-03	1610

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.79 E-02	43991

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.65 E-04	892
Ag Filler	75	1.70 E-03	2675

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
6.34 E-01	1000000

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ADI Proprietary